

## 60V N-Channel Enhancement Mode MOSFET

### Description

The NP6008N uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

- ◆  $V_{DS} = 60V$   $I_D = 10A$   
 $R_{DS(ON)} < 25m\Omega$  @  $V_{GS} = 10V$  (Typ: 21m  $\Omega$ )  
 $R_{DS(ON)} < 28m\Omega$  @  $V_{GS} = 4.5V$  (Typ: 25m  $\Omega$ )
- ◆ High density cell design for ultra low Rdson.
- ◆ Fully characterized avalanche voltage and current.
- ◆ Low gate to drain charge to reduce switching losses.

### Application

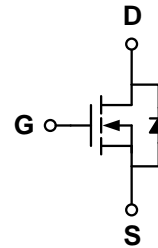
- ◆ Power switching application.
- ◆ Hard switched and high frequency circuits.
- ◆ Uninterruptible power supply.

### Package

- ◆ SOT-223



### Schematic diagram

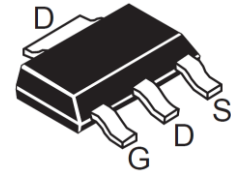


### Marking and pin assignment

#### SOT-223

(Top View)

**NP6008N**  
**XXXX**  
**YYYY**



NP: Natlinear Power  
 6008: 60V8A  
 N: SOT-223

XXXX: Wafer Lot No.  
 YYYY: Quality Code

### Ordering Information

| Part Number | Storage Temperature | Package | Devices Per Reel |
|-------------|---------------------|---------|------------------|
| NP6008N-G   | -55°C to +150°C     | SOT-223 | 3000             |

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| parameter                             |         | symbol   | limit   | unit |
|---------------------------------------|---------|----------|---------|------|
| Drain-source voltage                  |         | $V_{DS}$ | 60      | V    |
| Gate-source voltage                   |         | $V_{GS}$ | ±20     | V    |
| Continuous Drain Current              | TC=25°C | $I_D$    | 8       | A    |
|                                       | TC=70°C |          | 6       |      |
| Pulsed Drain Current                  |         | $I_{DP}$ | 32      | A    |
| Avalanche Current                     |         | $I_{AS}$ | 15      | A    |
| Avalanche energy( L=0.1mH)            |         | EAS      | 11      | mJ   |
| Maximum power dissipation             | TC=25°C | $P_D$    | 3       | W    |
| Power Dissipation – Derate above 25°C | TC=75°C |          | 2       |      |
| Operating junction Temperature range  |         | $T_j$    | -55—150 | °C   |

**Electrical Characteristics** (TA=25°C unless otherwise noted)

| Parameter                                     | Symbol                              | Condition                                                                                                     | Min | Typ | Max  | Unit  |
|-----------------------------------------------|-------------------------------------|---------------------------------------------------------------------------------------------------------------|-----|-----|------|-------|
| <b>Static Characteristics</b>                 |                                     |                                                                                                               |     |     |      |       |
| Drain-source breakdown voltage                | BV <sub>DSS</sub>                   | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA                                                                    | 60  | -   | -    | V     |
| BVDSS Temperature Coefficient                 | ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | Reference to 25°C, I <sub>D</sub> =1mA                                                                        |     | 33  |      | mV/°C |
| Zero gate voltage drain current               | I <sub>DSS</sub>                    | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V                                                                     | -   | -   | 1    | μA    |
|                                               |                                     | T <sub>J</sub> =85°C                                                                                          | -   | -   | 30   |       |
| Gate Leakage Current                          | I <sub>GSS</sub>                    | V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V                                                                    | -   | -   | ±100 | nA    |
| Gate threshold voltage                        | V <sub>GS(th)</sub>                 | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                                      | 1.2 | 1.9 | 2.5  | V     |
| Drain-source on-state resistance <sup>1</sup> | R <sub>DS(ON)</sub>                 | V <sub>GS</sub> =10V, I <sub>D</sub> =8A                                                                      | -   | 21  | 25   | mΩ    |
|                                               |                                     | V <sub>GS</sub> =4.5V, I <sub>D</sub> =7A                                                                     |     | 25  | 28   |       |
| On Status Drain Current                       | I <sub>D(ON)</sub>                  | V <sub>DS</sub> =10V, V <sub>GS</sub> =10V                                                                    | 10  | -   | -    | A     |
| <b>Diode Characteristics</b>                  |                                     |                                                                                                               |     |     |      |       |
| Diode Forward Voltage                         | V <sub>SD</sub>                     | I <sub>SD</sub> =1A, V <sub>GS</sub> =0V                                                                      | -   | 0.8 | 1.1  | V     |
| Diode Continuous Forward Current              | I <sub>S</sub>                      |                                                                                                               | -   | -   | 10   | A     |
| Reverse Recovery Time                         | t <sub>rr</sub>                     | I <sub>F</sub> =10A,                                                                                          | -   | 35  | -    | ns    |
| Reverse Recovery Charge                       | Q <sub>rr</sub>                     | dI/dt=100A/us                                                                                                 | -   | 43  | -    | nC    |
| <b>Dynamic Characteristics<sup>2</sup></b>    |                                     |                                                                                                               |     |     |      |       |
| Gate Resistance                               | R <sub>G</sub>                      | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz                                                              | -   | 3   | -    | Ω     |
| Input capacitance                             | C <sub>ISS</sub>                    | V <sub>GS</sub> =0V, V <sub>DS</sub> =25V<br>f=1.0MHz                                                         | -   | 720 | -    | pF    |
| Output capacitance                            | C <sub>OSS</sub>                    |                                                                                                               | -   | 150 | -    |       |
| Reverse transfer capacitance                  | C <sub>RSS</sub>                    |                                                                                                               | -   | 90  | -    |       |
| Turn-on delay time                            | t <sub>D(ON)</sub>                  | V <sub>GS</sub> =10V, V <sub>DD</sub> =30V,<br>R <sub>L</sub> =4.7Ω, I <sub>D</sub> =7A, R <sub>G</sub> =3.3Ω | -   | 8   | -    | ns    |
| Turn-on Rise time                             | t <sub>r</sub>                      |                                                                                                               | -   | 5   | -    |       |
| Turn-off delay time                           | t <sub>D(OFF)</sub>                 |                                                                                                               | -   | 29  | -    |       |
| Turn-off Fall time                            | t <sub>f</sub>                      |                                                                                                               | -   | 6   | -    |       |
| Total gate charge                             | Q <sub>g</sub>                      | V <sub>GS</sub> =10V, I <sub>D</sub> =8A<br>V <sub>DS</sub> =30V                                              | -   | 16  |      | nC    |
| Gate-source charge                            | Q <sub>gs</sub>                     |                                                                                                               |     | 2.7 |      |       |
| Gate-drain charge                             | Q <sub>gd</sub>                     |                                                                                                               | -   | 4.4 | -    |       |

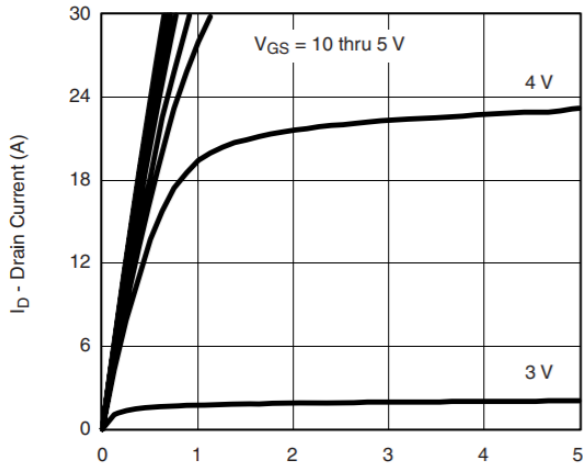
Note: 1: Pulse test; pulse width ≦ 300ns, duty cycle ≦ 2%.

2: Guaranteed by design, not subject to production testing.

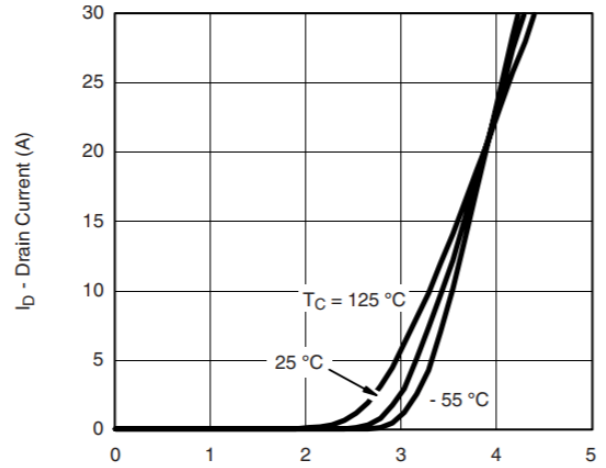
**Thermal Characteristics**

| Parameter                              | Symbol | Typical | Unit |
|----------------------------------------|--------|---------|------|
| Thermal Resistance-Junction to Case    | Rθjc   | 1.7     | °C/W |
| Thermal Resistance junction-to ambient | Rθja   | 62.5    |      |

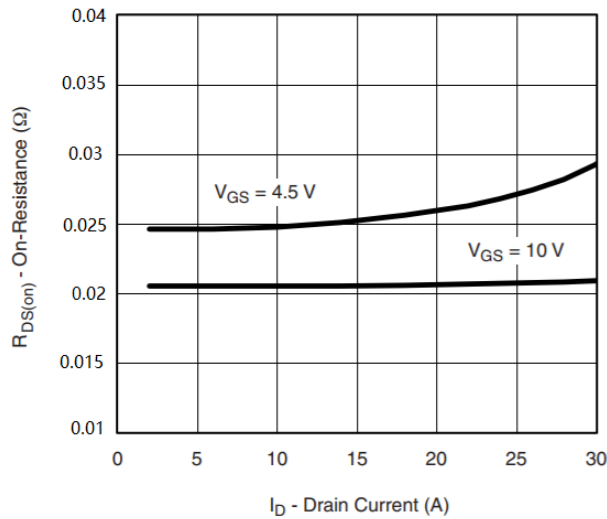
## Typical Performance Characteristics



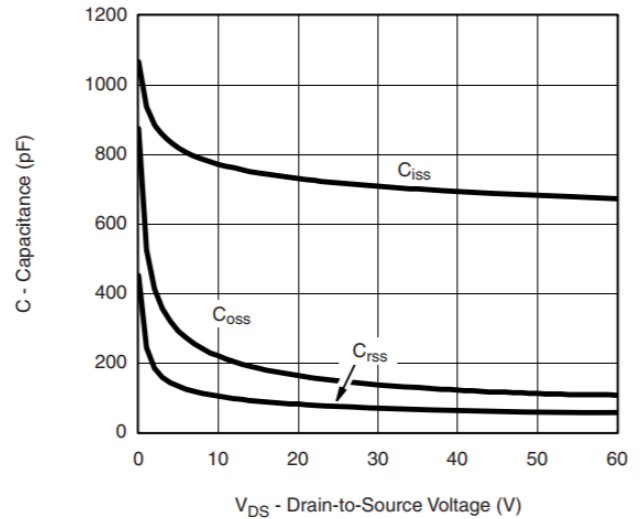
$V_{GS} = 10$  thru 5 V  
4 V  
3 V  
 $V_{DS}$  - Drain-to-Source Voltage (V)  
**Output Characteristics**



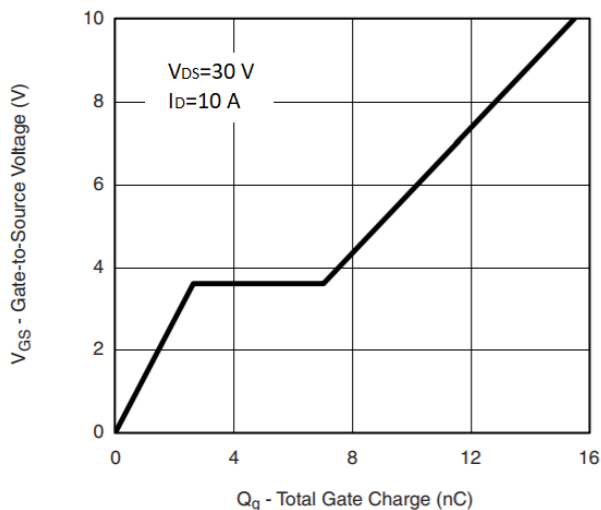
$T_C = 125^\circ\text{C}$   
 $25^\circ\text{C}$   
 $-55^\circ\text{C}$   
 $V_{GS}$  - Gate-to-Source Voltage (V)  
**Transfer Characteristics**



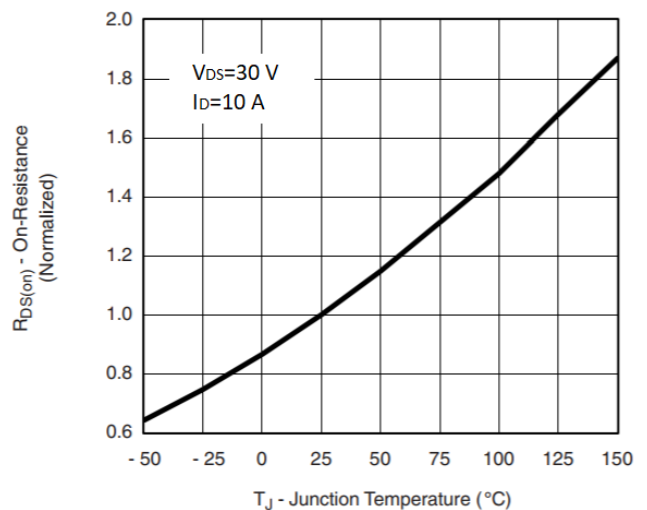
$V_{GS} = 4.5$  V  
 $V_{GS} = 10$  V  
 $I_D$  - Drain Current (A)  
**On-Resistance vs. Drain Current**



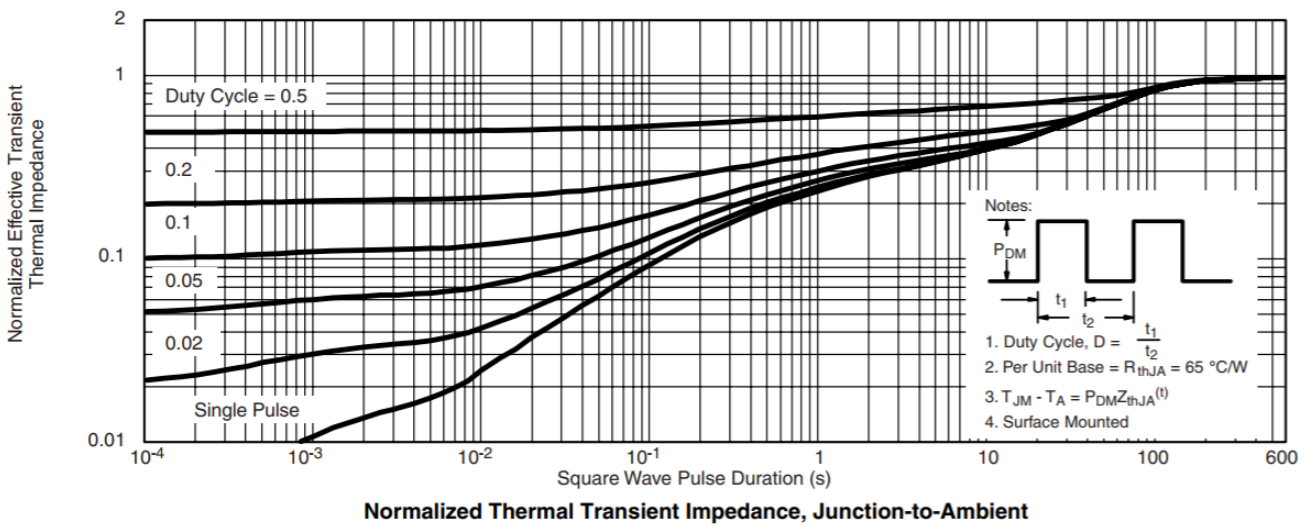
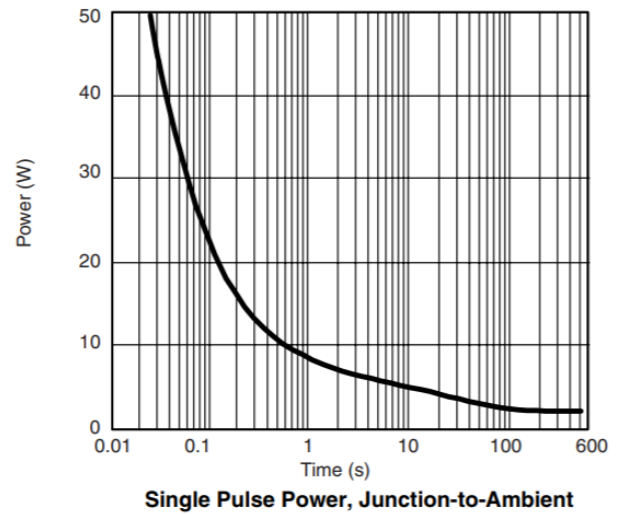
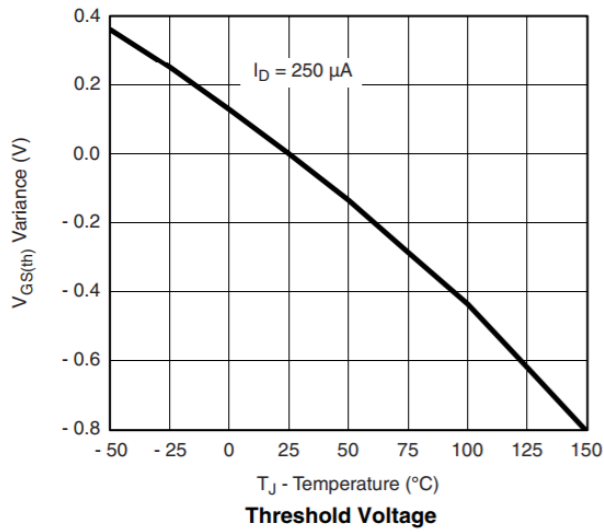
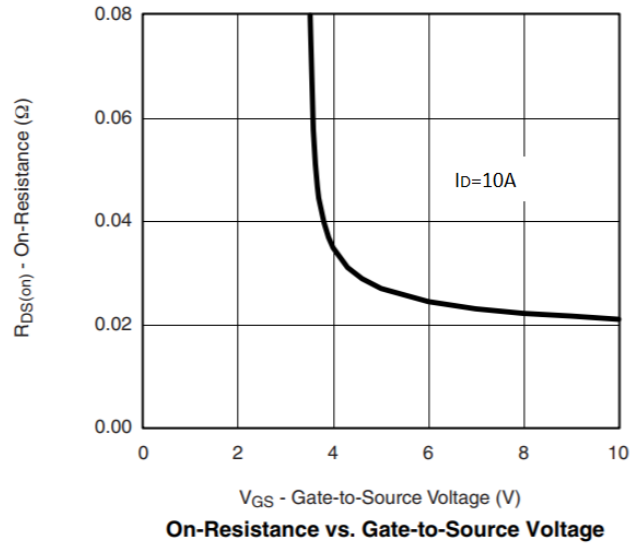
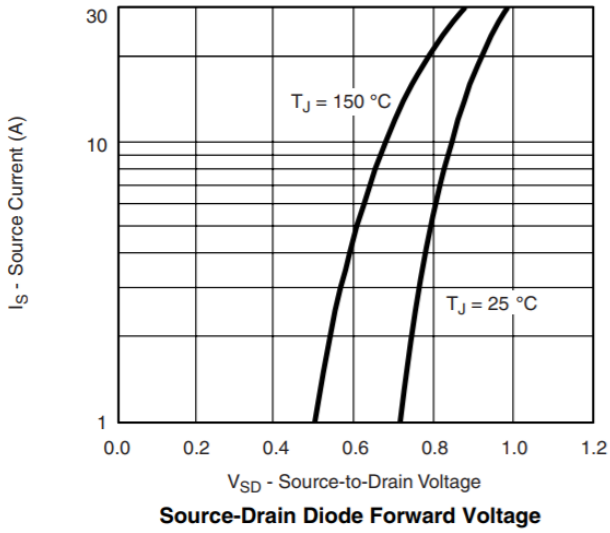
$C_{iss}$   
 $C_{oss}$   
 $C_{rss}$   
 $V_{DS}$  - Drain-to-Source Voltage (V)  
**Capacitance**



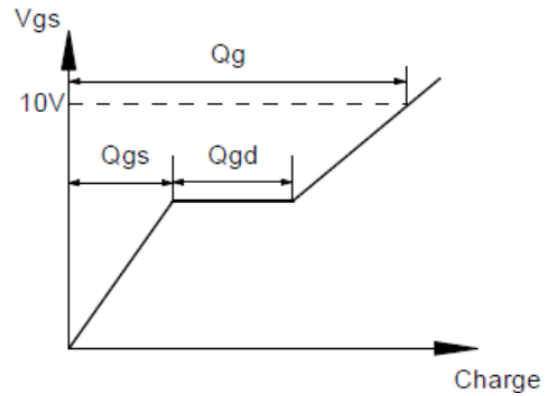
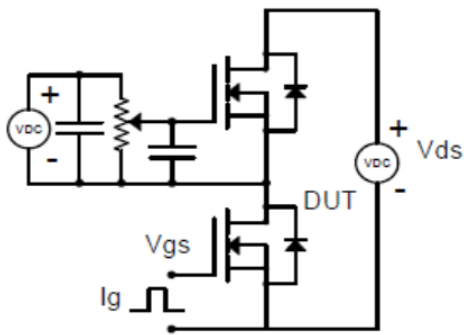
$V_{GS} = 30$  V  
 $I_D = 10$  A  
 $Q_g$  - Total Gate Charge (nC)  
**Gate Charge**



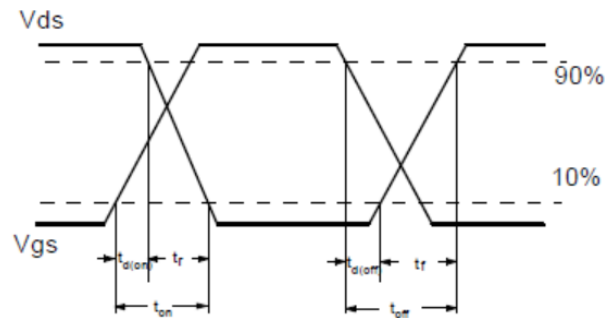
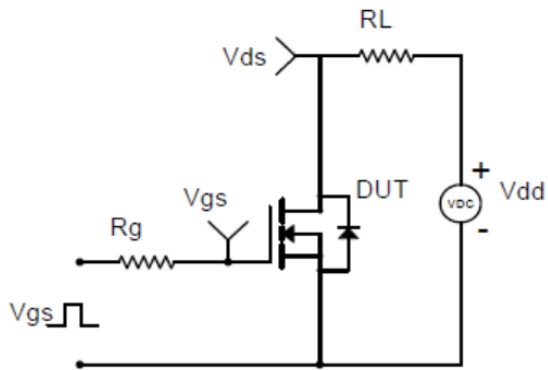
$V_{DS} = 30$  V  
 $I_D = 10$  A  
 $T_J$  - Junction Temperature ( $^\circ\text{C}$ )  
**On-Resistance vs. Junction Temperature**



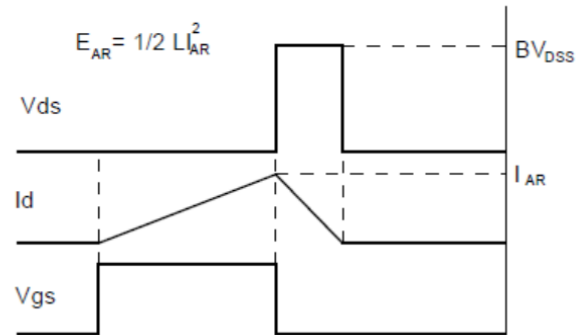
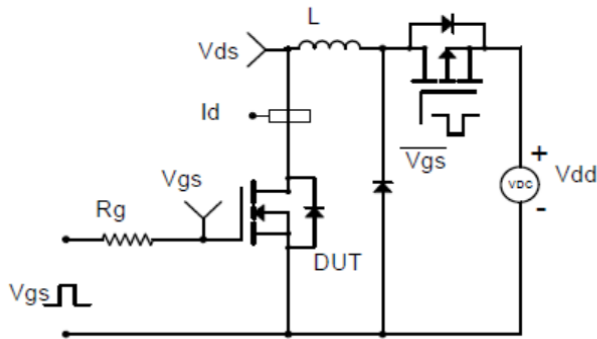
Gate Charge Test Circuit & Waveform



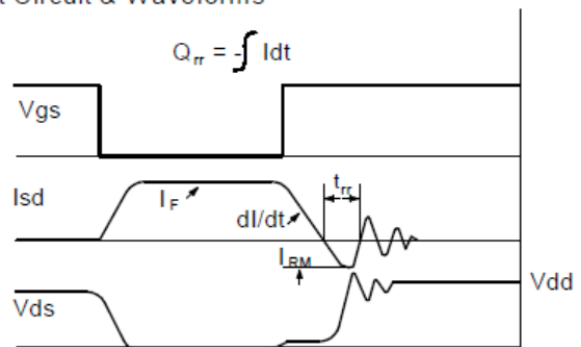
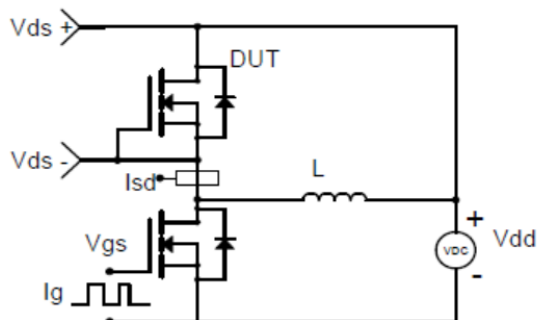
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

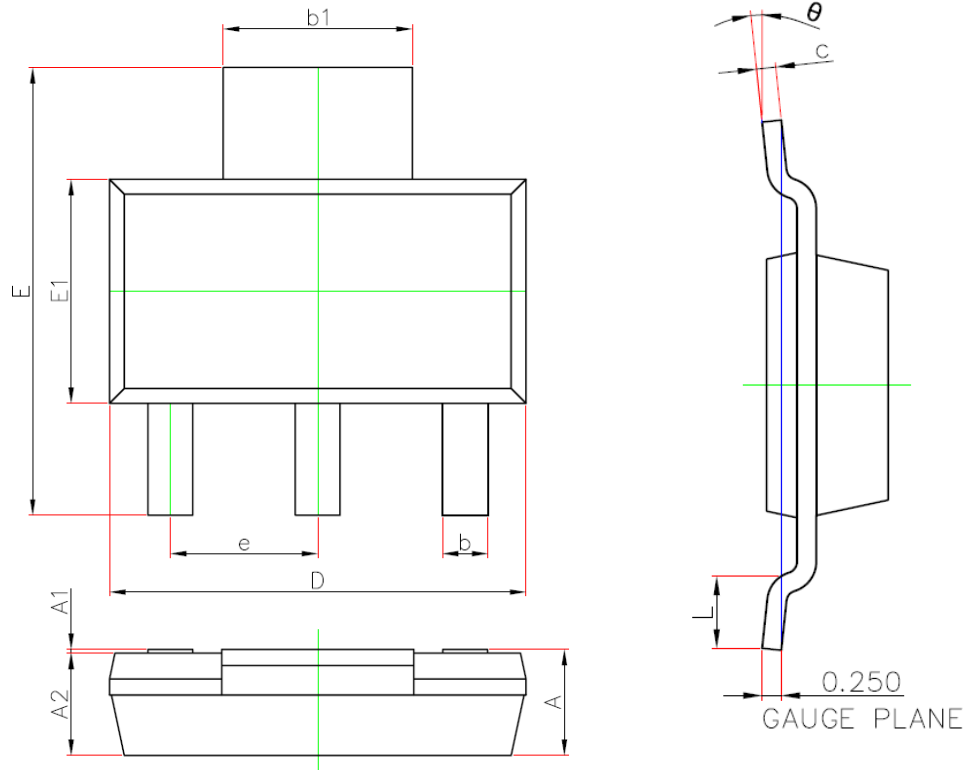


Diode Recovery Test Circuit & Waveforms



## Package Information

- SOT-223



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min.                      | Max.  | Min.                 | Max.  |
| A      | —                         | 1.800 | —                    | 0.071 |
| A1     | 0.020                     | 0.100 | 0.001                | 0.004 |
| A2     | 1.500                     | 1.700 | 0.059                | 0.067 |
| b      | 0.660                     | 0.840 | 0.026                | 0.033 |
| b1     | 2.900                     | 3.100 | 0.114                | 0.122 |
| c      | 0.230                     | 0.350 | 0.009                | 0.014 |
| D      | 6.300                     | 6.700 | 0.248                | 0.264 |
| E      | 6.700                     | 7.300 | 0.264                | 0.287 |
| E1     | 3.300                     | 3.700 | 0.130                | 0.146 |
| e      | 2.300(BSC)                |       | 0.091(BSC)           |       |
| L      | 0.750                     | —     | 0.030                | —     |
| θ      | 0°                        | 10°   | 0°                   | 10°   |